



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: SM-0504-03	DATE: April 6, 2005	MEANS OF DISTINGUISHING CHANGED DEVICES:
Product Affected: BF/BFG 100 (Refer Attachment II for the affected part numbers)		<input type="checkbox"/> Product Mark <input type="checkbox"/> Back Mark <input type="checkbox"/> Date Code <input checked="" type="checkbox"/> Other Change in unit quantity per tray
Date Effective: May 2, 2005		

Contact: Mary Vesey Title: Quality Assurance Manager Phone #: (831)-754- 4565 Fax #: (831)-754-4672 E-mail: mary.vesey@idt.com	Attachment:: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Samples: N/A
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DESCRIPTION AND PURPOSE OF CHANGE:

Die Technology
 Wafer Fabrication Process
 Assembly Process
 Equipment
 Material
 Testing
 Manufacturing Site
 Data Sheet
 Other

To change new revision of tray with different tray matrix for BF/BFG100. Tray is compliant to JEDEC 95 Standards. Tray size (outside dimensions) will remain the same. New revision of tray provides better pick & place process on equipment.

Description	Current Tray	New Tray
IDT Drawing# :	MSC-1703	MSC-1776
Quantity Per Tray :	250 units	240 units
Pocket Size :	10mm x 10mm	10mm x 10 mm
Tray Matrix :	10 x 25	10 x 24

RELIABILITY/QUALIFICATION SUMMARY:

There is no change in quality and reliability of the affected parts.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ **Approval for shipments prior to effective date.**

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT I - PCN: SM-0504-03

Qual Plan : BC4-07-01

Test Vehicle :10 mm x10 mm Shipping Tray

Qualification Test Plan and Result:

Description	Evaluation Result	Status
A. PACKAGING MATERIAL QUAL		
i) Package Fit in Pocket Test – Place a unit in a tray pocket. Rejects if a) Any lead or solder ball touches any part of the tray (wall or platform). Note : Not applicable to VFQPF-N packages. b) Unit NOT sitting firmly in pocket and movement > 20 mils on left to right or top to bottom.	OK	Done
ii) Tray Interface Check - Complete fill the tray pockets with units and places a cover tray on top. Strap the trays with Velcro Strap and vigorously shake the stack in a live and dead bug position 30 times. Remove the straps and cover tray. Reject if : a) Any damages to the units or package dislodged from its pockets. b) Any scratches on the package (included surface scratches)	OK	Done
iii) Complete fill the tray pockets with units and tilt the units in the pocket into slanting position Reject if : a) Any contact between top cover tray with units. b) Any scratches or chip on the package.	OK	Done
iv) Complete fill the tray pockets with units and places a cover tray on top. Press the top cover tray until contact with the bottom tray. Then remove the top cover tray properly. Reject if: a) The bottom tray sticks with top cover tray. b) Any unit sticks to the bottom pocket of top cover tray.	OK	Done
v) Chip or crack test – Drop tray on 4 sides, top and bottom from a distance of 20 inches on a concrete floor. Reject if any chips and cracks on the trays.	OK	Done
vi) Unit shall not drop out from the tray pocket during machine placement or transportation	OK	Done
vii) Tray shall be free of foreign particles, wet or oily build-up, or any types of contamination	OK	Done
viii) Fresh tray from supplier shall be free of chips and crack	OK	Done
ix) Tray shall be no pits or scratches greater than 40 mils on length or 20 mils in depth that would impact the normal use of the tray	OK	Done
x) Incomplete fill of any part of the tray shall not more than 100 mils maximum in any direction.	OK	Done
xi) Incomplete fill of any part of the tray shall not more than 100 mils maximum in any direction.	OK	Done
xii) For tray pocket fences, 75% of the fences length should be with at least 75% of the fence's height.	OK	Done
xiii) Tray shall meet IDT (Assembly, Test and Backend area) equipment input and output tooling	OK	Done
xiv) Pass Static Electricity Test (100 volt max)	OK	Done
xv) Surface Resistivity reading (between 1x10 ⁵ to 1x10 ¹¹ ohms per sq.)	OK	Done
xvi) Must pass IDT bake test.	OK	Done
xvii) Must pass Standard Drop Test a) 3-fs drop test (For BGA and substrate only) b) 6-fs drop test	Height : 3fts (normal packing) 30x Inspection : 924/924 Observation : no abnormality. Height : 6fts (normal packing) Inspection result: 924/924 30x Inspection : 924/924 Observation : no abnormality	Done
xviii) Tray must be flip-able design.	OK	Done
B. COPLAN		
Lead/ Ball Inspection Machine	Machine buy-off result :- - M/c : CI-9450 - Jam Rate : 0/720 - P&P : 0/720 - UPH : 8640	Done



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ATTACHMENT II - PCN: SM-0504-03

Affected Part Number:

IDT Part No	IDT Part No	IDT Part No
IDT709159L6BF	IDT70T34L20BF	IDT70V9159L7BFI
IDT709159L7BF	IDT70T34L25BF	IDT70V9159L9BF
IDT709159L7BFI	IDT70T34L25BFI	IDT70V9159L9BFI
IDT709159L9BF	IDT70T35L20BF	IDT70V9169L6BF
IDT709159L9BFI	IDT70T35L25BF	IDT70V9169L7BF
IDT709169L6BF	IDT70T35L25BFI	IDT70V9169L7BFI
IDT709169L7BF	IDT70T9159L12BF	IDT70V9169L9BF
IDT709169L7BFI	IDT70T9159L12BFI	IDT70V9169L9BFI
IDT709169L9BF	IDT70T9159L7BF	IDT70V9349L6BF
IDT709169L9BFI	IDT70T9159L9BF	IDT70V9349L7BF
IDT709349L6BF	IDT70T9159L9BFI	IDT70V9349L7BFI
IDT709349L7BF	IDT70T9169L12BF	IDT70V9349L9BF
IDT709349L7BFI	IDT70T9169L12BFI	IDT70V9349L9BFI
IDT709349L9BF	IDT70T9169L7BF	IDT70V9359L6BF
IDT709349L9BFI	IDT70T9169L9BF	IDT70V9359L7BF
IDT709359L6BF	IDT70T9169L9BFI	IDT70V9359L7BFI
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IDT70T15L20BF	IDT70V24L15BF	
IDT70T15L25BF	IDT70V24L20BF	
IDT70T15L25BFI	IDT70V24L20BFI	
IDT70T16L20BF	IDT70V24L25BF	
IDT70T16L25BF	IDT70V24L55BF	
IDT70T16L25BFI	IDT70V24VL55BF	
IDT70T24L20BF	IDT70V24VL55BFI	
IDT70T24L25BF	IDT70V25L15BF	
IDT70T24L25BFI	IDT70V25L20BF	
IDT70T25L20BF	IDT70V25L25BF	
IDT70T25L25BF	IDT70V9159L6BF	
IDT70T25L25BFI	IDT70V9159L7BF	



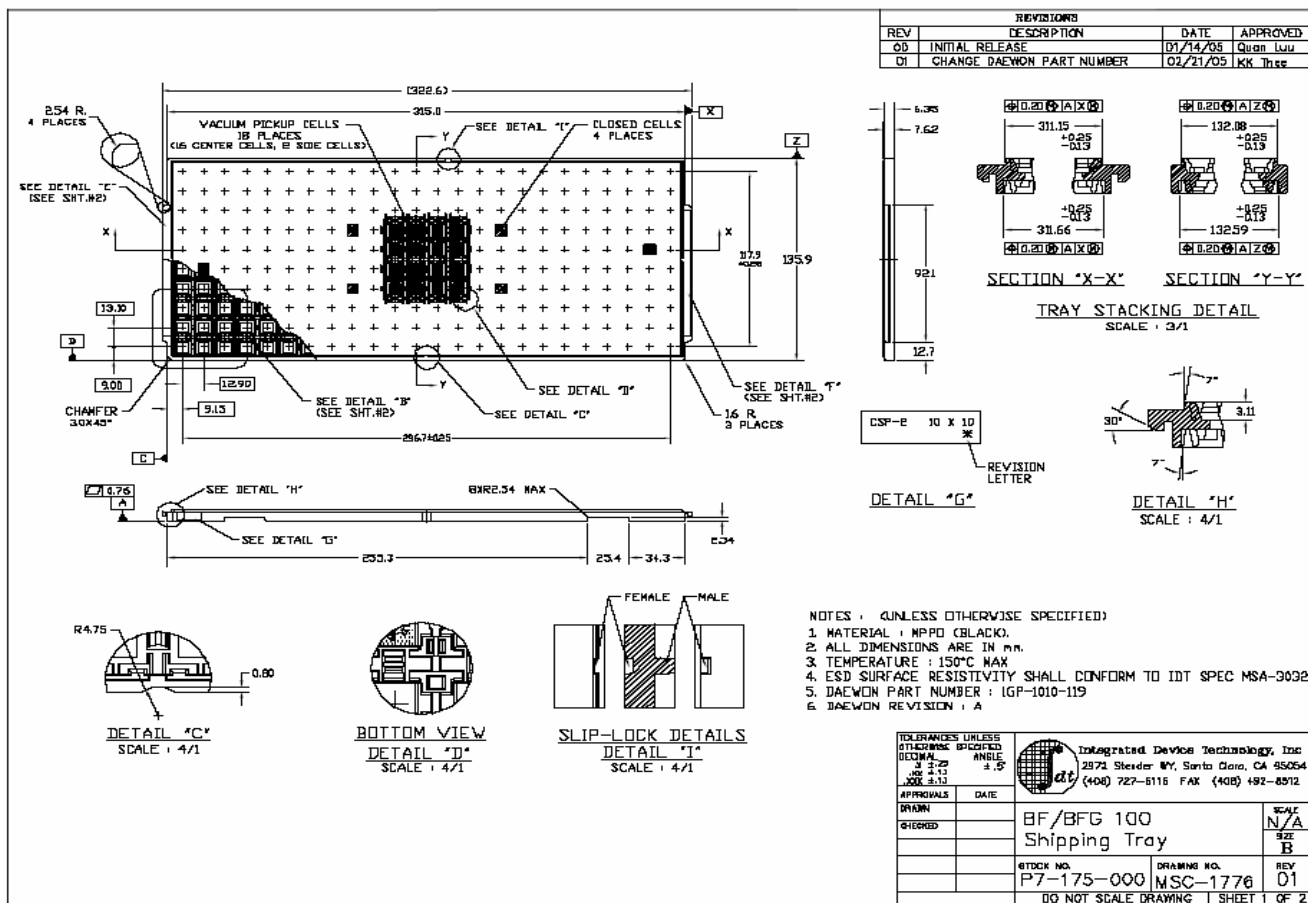
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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT III - PCN: SM-0504-03

TRAY DRAWING I





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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT III - PCN: SM-0504-03

TRAY DRAWING II

